

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L13	1418	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L14	541	L13 and (@ad<"20030416") and ((silica adj ceramic) or ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L15	2554	(257/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L16	83	L13 and (@ad<"20030416") and ((heat adj (radiating or radiation))) not L14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L17	324	L15 and (@ad<"20030416") and ((heat adj (radiating or radiation))) not (L14 and L16)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L18	2644	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26

L19	98	L18 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L20	3076	(438/122,125,108).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L21	114	L20 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17 not L19)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L22	1944	(257/e23.103,e23.105,e23.111,e23.127,e23.18).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L23	180	L22 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17 not L19 not L21)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26
L24	423	(semiconductor) and (flip adj chip) and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17 and L19 and L21 and L23)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:27

L25	2920	(semiconductor) and (chip) and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17 and L19 and L21 and L23) not 24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:27
L26	2920	(semiconductor) and (chip) and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17 and L19 and L21 and L23) not L24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:27
L27	1746	(semiconductor) and (chip) and (substrate) and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (L14 and L16 and L17 and L19 and L21 and L23) not L24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:31
L28	10176	((257/706,712,778,e23.103,e23.105,e23.111,e23.127,e23.18) or (438/122,125,108)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:32
L29	3263	28 and (@ad<"20030416") and (heat adj (sink or spread\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:33
S1	1418	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:04

S2	541	S1 and (@ad<"20030416") and ((silica adj ceramic) or ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:27
S3	2554	(257/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:27
S4	445	S3 and (@ad<"20030416") and ((silica adj ceramic) or ceramic) not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:27
S5	83	S1 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:32
S6	324	S3 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (S2 and S5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:49
S7	2644	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:49

S8	98	S7 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (S2 and S5 and S6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:54
S9	3076	(438/122,125,108).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 10:54
S10	114	S9 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (S2 and S5 and S6 not S8)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:00
S11	1944	(257/e23.103,e23.105,e23.111,e23.127,e23.18).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:00
S12	180	S11 and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (S2 and S5 and S6 not S8 not S10)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:10
S13	3343	(semiconductor) and (chip) and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (S2 and S5 and S6 and S8 and S10 and S12)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:12

S14	1053	S13 and (terminal\$1) and (substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 11:11
S15	423	(semiconductor) and (flip adj chip) and (@ad<"20030416") and ((heat) adj (radiating or radiation)) not (S2 and S5 and S6 and S8 and S10 and S12)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/23 13:26